

FORM PTO-1449 LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT (Use several sheets if necessary)	ATTY. DOCKET NO. 100111595-1	SERIAL NO.
	APPLICANT BASH et al.	
	FILING DATE filed concurrently	GROUP

1021 U.S. PTP
10/02/12
12/14/01

REFERENCE DESIGNATION

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS

42
1/28/02
M. P. Rudger

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	TRANSLATION	
						YES	NO

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, etc.)

<p><i>J.P.?</i></p>	<p>R. Hannemann, L. R. Fox and M. Mahalingham, "Thermal Design for Microelectronic Components," in "Advances in Cooling Techniques for Computers" 245-276 (Win Aung ed., Hemisphere Publishing Corporation, 1991).</p>
<p><i>J.P.?</i></p>	<p>"Advances in Cooling Techniques for Computers" 150-153 (Win Aung ed., Hemisphere Publishing Corporation, 1991).</p>
<p><i>J.P.?</i></p>	<p>Robert Darveaux and Iwona Turlik, "Backside Cooling of Flip Chip Devices in Multichip Modules," ICMCM Proc. 230-241 (1992).</p>

EXAMINER

DATE CONSIDERED

1/21/03

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LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT

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ATTY. DOCKET NO.

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10/022112
U.S. PRO

12/14/01

REFERENCE DESIGNATION

U.S. PATENT DOCUMENTS

[illegible]

FOREIGN PATENT DOCUMENTS

[illegible]

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, etc.)

P7	Herman W. Chu, Christian L. Belady and Chandrakant D. Patel, "A Survey of High-performance, High Aspect Ratio, Air Cooled Heat Sinks," International Systems and Packaging Symposium (1999).
P7	Chandrakant D. Patel, "Backside Cooling Solution for High Power Flip Chip Multi-Chip Modules," IEEE ECTC Proceedings 442-449 (May, 1994).

EXAMINER

DATE CONSIDERED